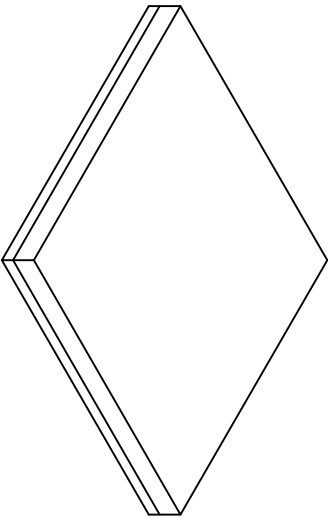


REV	DESCRIPTION	DATE	BY
00	INITIAL RELEASE PER DGN C8492	03/28/00	ADEBO
01	ADDED 176 FOOTPRINT, UPDATED FORMAT	01/26/01	GREME



7. REFERENCE SPECIFICATIONS:  
 A. AMW SPEC #001-0531-2234; PACKING OPERATION PROCEDURE.  
 B. AMW SPEC #001-0519-2092; MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.  
 5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 196.  
 3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 14 X 14.  
 2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.  
 1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS	THIRD ANGLE PROJECTION	DATE	APPROVALS	DESIGNED BY	DATE	APPROVALS	DATE	APPROVALS	DATE
		03/15/00	ADEBO	03/15/00					
		03/15/00	DARNO	03/15/00					
		03/15/00	TPANC	03/15/00					
		03/28/00	GSCHU	03/28/00					



PACKAGE OUTLINE - MAF, 14 X 14 MATRIX, 15.00mm X 15.00mm X 1.40mm, 0.70mm MOLD CAP, 0.48mm BALL, 1.00mm PITCH, LAMINATE SUBSTRATE, AMW

DO NOT SCALE DRAWING	SCALE	8:1
DATE	01/26/01	
REV	01	
SHEET	1 OF 3	